

ChipFill® - Hot applied surface defect repair system

General information:

Use:	Temporary repairing of potholes with a maximum depth of 5 cm and maximum diameter of 20 cm.
	Temporary repairing of natural crack and joints.
	ChipFill® can be applied all year around, at low temperature extra heating is needed.
	ChipFill® that isn't used can easily be stored and used later.
Manufacturing control and ISO certification:	The manufacturer is ISO 9001 certified.

Performance:

	ChipFill® will set rapidly, permitting the access route to be re-opened for traffic approx. 30 minutes after application start.
	ChipFill®s thermoplastic property makes it capable of conforming to the surface structure/geometry.
	ChipFill®s thermoplastic property makes it easy to avoid unevenness.
	ChipFill® has an even black colour throughout.
	ChipFill®s binder system ensure a good bonding to the underground.
	ChipFill®s binder system has incorporated elasticity so it follows contours of underground.
	High skid resistant surface (>55 SRT). Post sprinkle glass grains for high initial friction. SRT are not affected by wear and tear.
	ChipFill® is for temporary repair of pot holes, cracks and joint.

Specific information:

Material:	Pigment:	Pigment is used to ensure that ChipFill® keeps the black colour throughout the products lifetime. The pigment contains no lead and chromates or other heavy metals. The pigment is evenly distributed throughout ChipFill®.
	Binder system:	The binder is composed of alkyd-based resins and polymer.

	Filler system:	The fillers are a mixture of calcium carbonates, sand and anti-skid material.
	Environmental resistance:	The material is resistant to deterioration by exposure to sunlight, water, salt or bad weather conditions and impervious to oil and motor fuels.
	Composition:	<p>Binder: 15-25% composed of alkyd based resin</p> <p>Pigments/Colors: 0-5% pigment free from heavy metals</p> <p>Filler: 65-85% natural material (e.g. sand)</p>
	VOC:	The material is VOC free.
	Density:	<p>Bulk Density: ~0,8 kg/liter</p> <p>Density after application: ~2 kg/liter</p>
	Environment	<p>ChipFill® is/has</p> <ul style="list-style-type: none"> - minimum of waste - energy is only used during the actual application, not during standstill or transportation
Application:		<p>The surface must be free of dirt, dust, chemicals and oily substances. Remove these by using a broom, high pressure water or consequently grinding.</p> <p>The surface must be totally dry before installation! Remove all moisture from the application area using the gas burner.</p> <p>If ChipFill® is compressed, then the bags can be dropped to the ground in order to separate the chips/pellets</p> <ol style="list-style-type: none"> 1. Fill in a layer of ChipFill® of maximum 15 mm, and heat the material to above 200°C with the gas burner. The heated ChipFill® will start to be fluent and follow the contexture of the hole. 1a. If the depth is extending 15mm in depth repeat point 1. Make sure all materials is liquid before adding a new layer of ChipFill®. The maximum hole or joint depth should not exceed 50 mm. 2. Make sure all material is melted. 3. To secure initial skid resistance and avoid ghost marking post-sprinkle anti-skid aggregates after application, while the material is still hot.
Storage:		<p>ChipFill® should be stored dry and at temperatures below 30°C.</p> <p>Don't stack the pallets on top of each other.</p>
Packaging:		<p>ChipFill® is delivered in bags of 12 kg.</p> <p>ChipFill® delivered as full pallet; 66 bags (792kg)</p>